



Final Product Change Notification

202503024F01 : PCA9555PW Wire Conversion from Gold to Copper

Note: This notice is NXP Company
Proprietary.

Issue Date: Apr 15, 2025 **Effective Date:** Jul 31, 2025

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Management summary

NXP will change the wire for the bonding process of the PCA9555PW product, from gold to copper for improved reliability and manufacturing logistics. This will align the manufacturing process and flow of this product to industry standard.

Change Category

- | | | | | |
|--|---|--|--|---|
| <input type="checkbox"/> Wafer
Fab
Process | <input type="checkbox"/> Assembly
Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test
Process | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer
Fab
Materials | <input checked="" type="checkbox"/> Assembly
Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test
Equipment | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer
Fab
Location | <input type="checkbox"/> Assembly
Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test
Location | <input type="checkbox"/> Electrical
spec./Test
coverage |
| <input type="checkbox"/> Firmware <input type="checkbox"/> Other | | | | |

Notification Overview

Description

ATBK will convert to copper wire for this product.

Reason

Copper wire will improve overall product reliability and reduce logistics risks in production, by moving the product, to standard, current production materials.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment Jul 31, 2025

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing data sheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by May 15, 2025.

In compliance with JEDEC J-STD-048, potential Last Time Buy orders shall be placed before Last Time Buy Date.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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